



⚠ HI Voltage ClassName: 50MIL  
 VIN HV Pri SW NMOS Drain  
 Vin and GND Requires Isolation

PCB Number: PMP9334  
 PCB Rev: B

PCB LOGO  
 Texas Instruments



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Designed for: Public Release		Mod. Date: 6/5/2015	
Project Title: LM5022 HV Isolated Flyback			
Number: PMP9334	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	
Drawn By:	File: PMP9334 15Vout RevB.SchDoc	Sheet: 1 of 1	
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	Size: B	

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